

FEATURES

- **BROAD BAND INTERNALLY MATCHED FET**
- **HIGH POWER**
P1dB= 48.0dBm at 7.7GHz to 8.5GHz
- **HIGH GAIN**
G1dB= 7.5dB at 7.7GHz to 8.5GHz
- **LOW INTERMODULATION DISTORTION**
IM3(MIN.)= -25dBc at Pout= 41dBm (Single Carrier Level)
- **HERMETICALLY SEALED PACKAGE**



RF PERFORMANCE SPECIFICATIONS (Ta= 25°C)

| CHARACTERISTICS | SYMBOL | CONDITIONS | UNIT | MIN. | TYP. | MAX. |
|--|--------|--|------|------|------|------|
| Output Power at 1dB Gain Compression Point | P1dB | VDS= 10V IDSset= 9.5A f= 7.7 to 8.5GHz | dBm | 47.0 | 48.0 | — |
| Power Gain at 1dB Gain Compression Point | G1dB | | dB | 6.5 | 7.5 | — |
| Drain Current | IDS1 | | A | — | 14.5 | 16.0 |
| Gain Flatness | ΔG | | dB | — | — | ±0.8 |
| Power Added Efficiency | ηadd | | % | — | 36 | — |
| 3rd Order Intermodulation Distortion | IM3 | Two-Tone Test Po= 41dBm, Δf= 5MHz (Single Carrier Level) | dBc | -25 | -30 | — |
| Drain Current | IDS2 | | A | — | — | 13.1 |
| Channel Temperature Rise | ΔTch | (VDS × IDS + Pin - P1dB) × Rth(c-c) | °C | — | — | 100 |

Recommended Gate Resistance(Rg): 28 Ω

ELECTRICAL CHARACTERISTICS (Ta= 25°C)

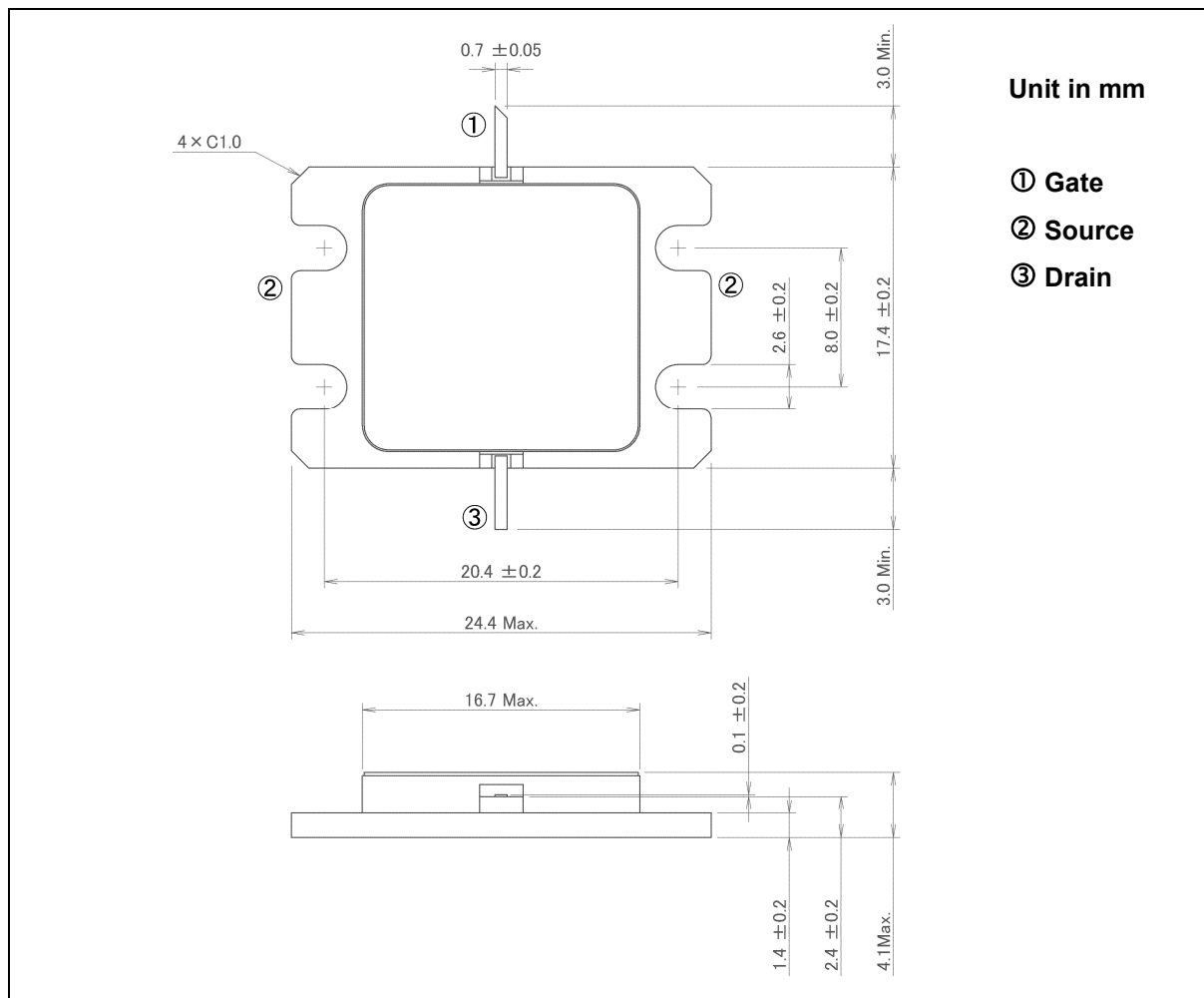
| CHARACTERISTICS | SYMBOL | CONDITIONS | UNIT | MIN. | TYP. | MAX. |
|-------------------------------|----------|-----------------------|------|------|------|------|
| Transconductance | gm | VDS= 3V IDS= 11.0A | S | — | 15.0 | — |
| Pinch-off Voltage | VGSoff | VDS= 3V IDS= 120mA | V | -1.0 | -1.8 | -2.5 |
| Saturated Drain Current | IDSS | VDS= 3V VGS= 0V | A | — | 27 | — |
| Gate-Source Breakdown Voltage | VGSO | IGS= -0.4mA | V | -5 | — | — |
| Thermal Resistance | Rth(c-c) | Channel to Case | °C/W | — | 0.8 | 1.0 |

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ABSOLUTE MAXIMUM RATINGS (Ta= 25°C)

| CHARACTERISTICS | SYMBOL | UNIT | RATING |
|------------------------------------|--------|------|-------------|
| Drain-Source Voltage | VDS | V | 15 |
| Gate-Source Voltage | VGS | V | -5 |
| Drain Current | IDS | A | 20.0 |
| Total Power Dissipation (Tc= 25°C) | PT | W | 150 |
| Channel Temperature | Tch | °C | 175 |
| Storage | Tstg | °C | -65 to +175 |

PACKAGE OUTLINE (7-AA09A)



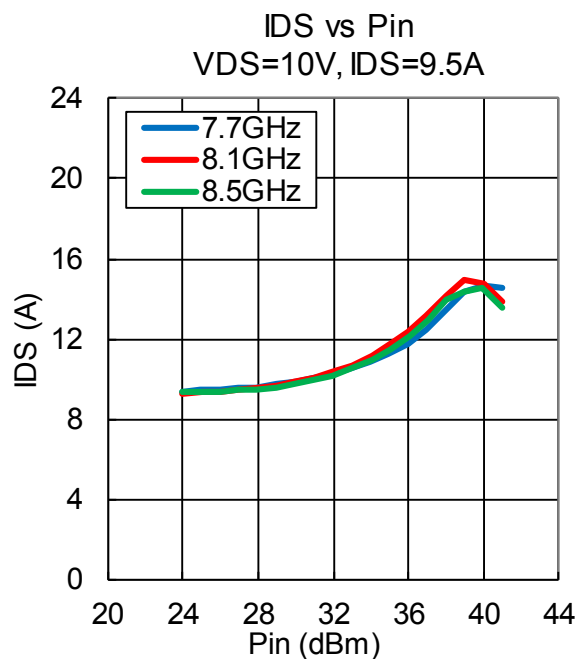
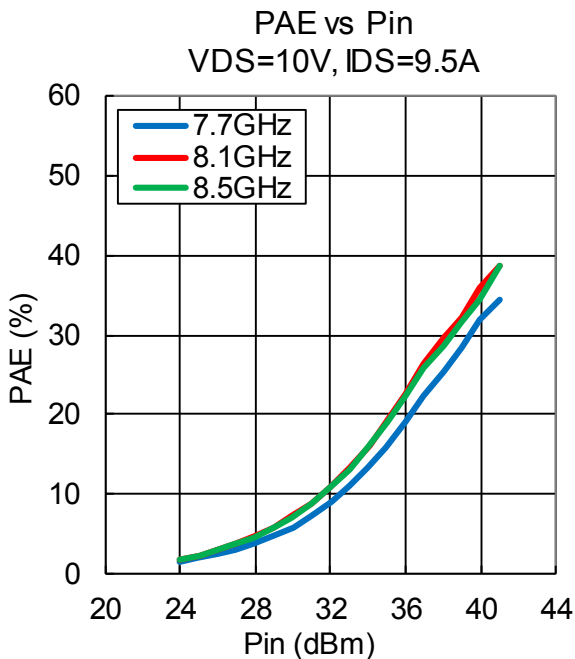
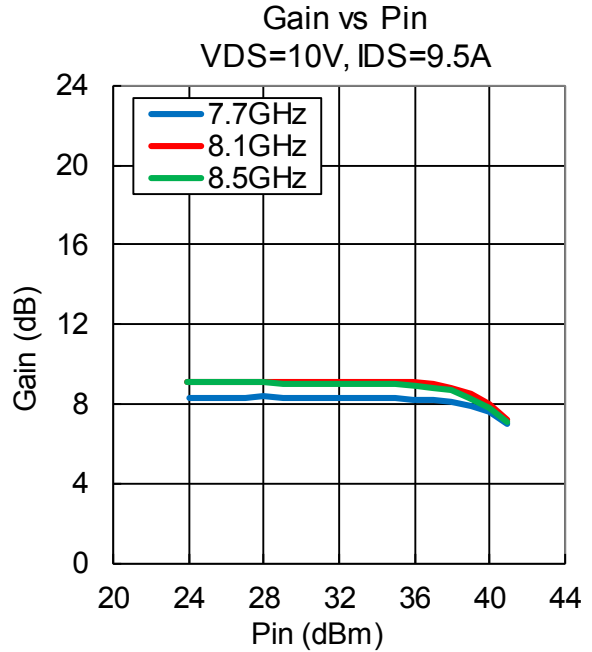
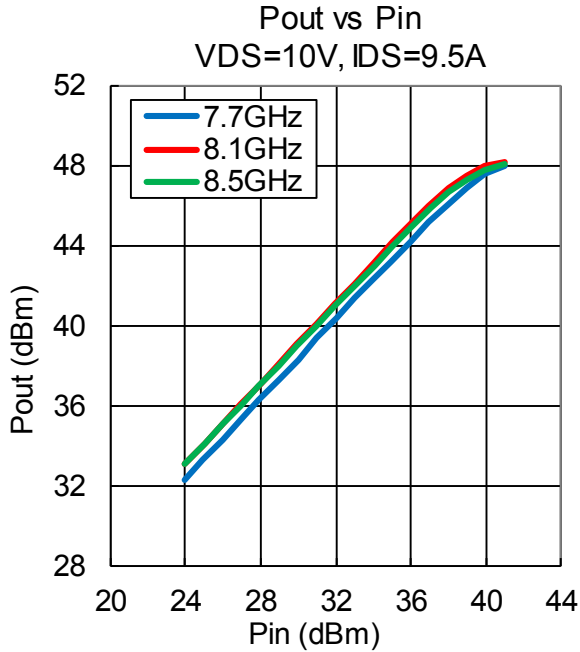
HANDLING PRECAUTIONS FOR PACKAGE MODEL

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C or 3 seconds at 350°C.

TYPICAL RF PERFORMANCE

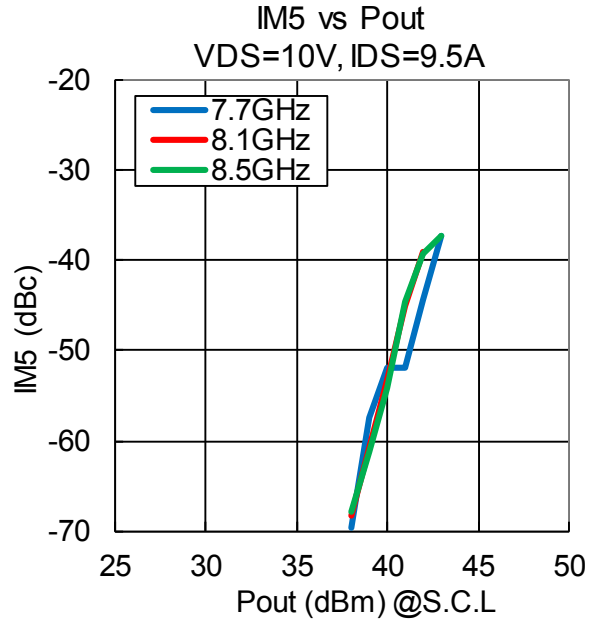
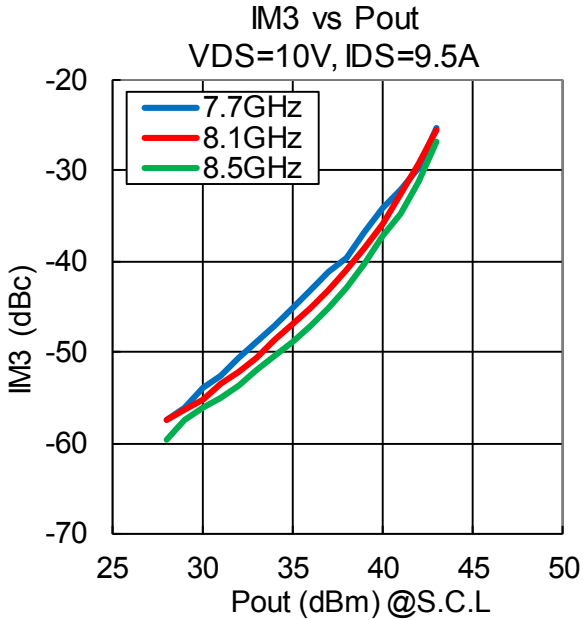
• Pout , Gain , PAE , IDS vs. Pin

VDS= 10 V, IDSset= 9.5 A, f= 7.7, 8.1, 8.5 GHz, Ta= +25 °C



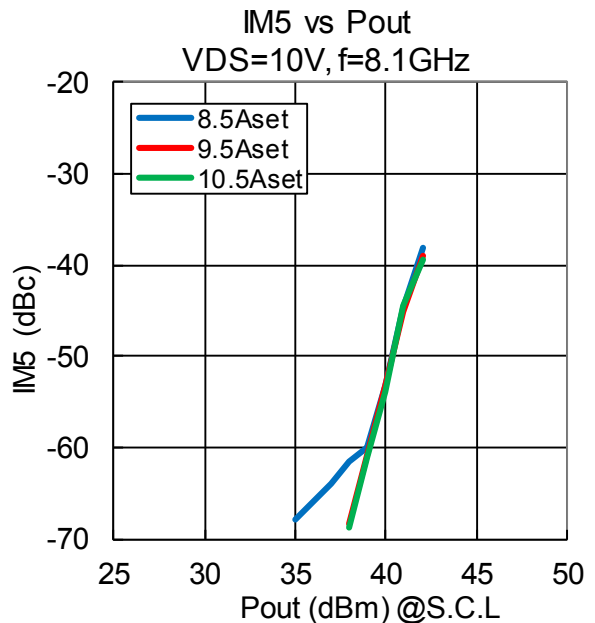
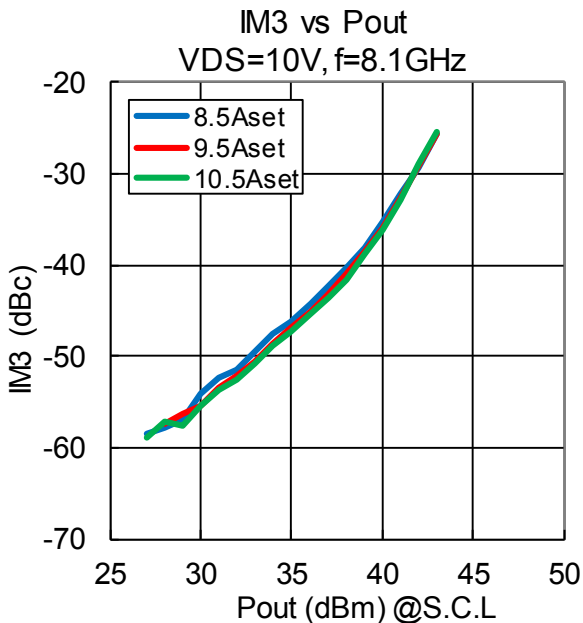
•IM3, IM5 vs. Pout

VDS= 10 V, IDSset= 9.5 A, f= 7.7, 8.1, 8.5 GHz, Δf= 5 MHz, Ta= +25 °C



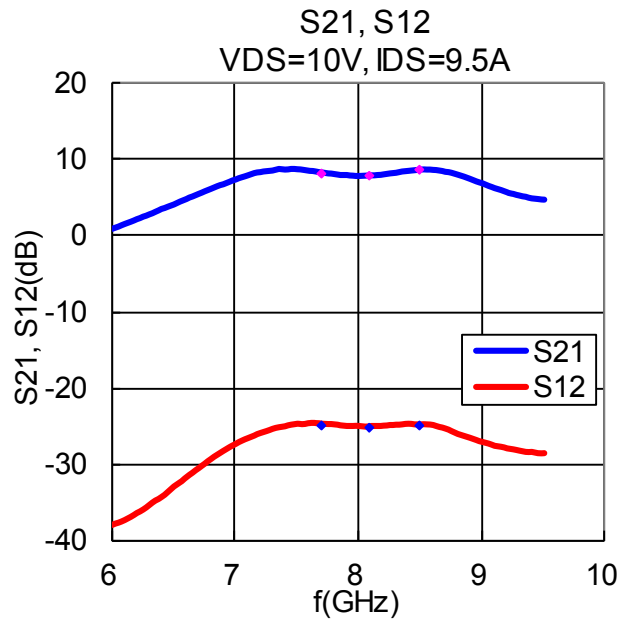
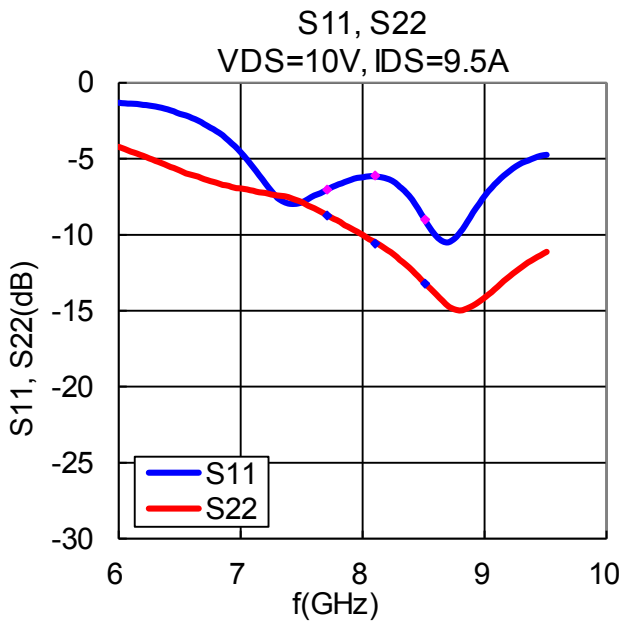
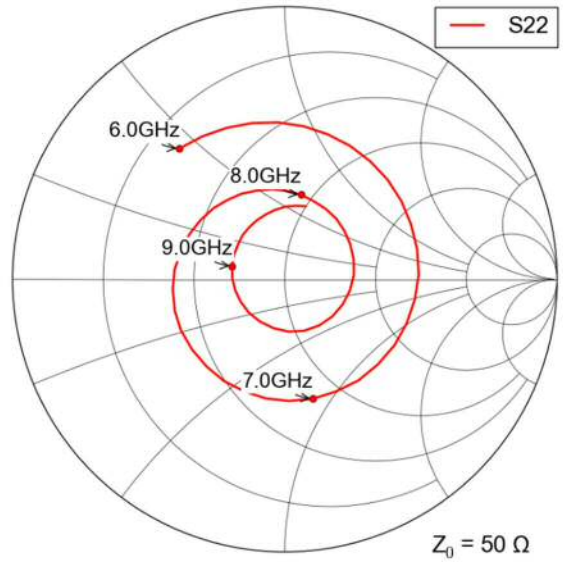
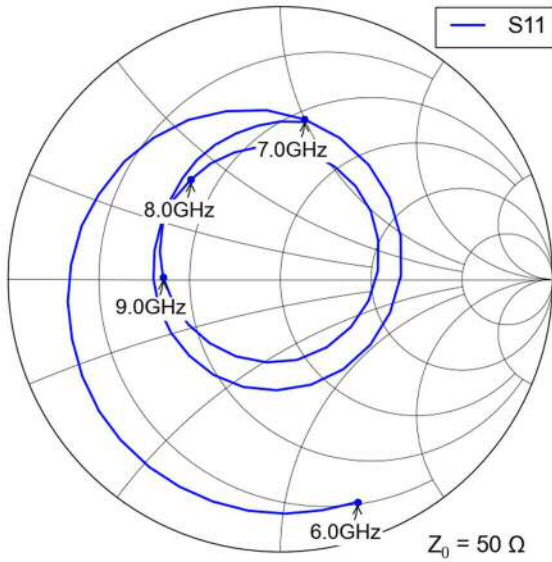
•IM3, IM5 vs. Pout

VDS= 10 V, IDSset= 8.5, 9.5, 10.5 A, f= 8.1 GHz, Ta= +25 °C



-S-Parameters

VDS= 10 V, IDSset= 9.5 A, f= 6.0 to 9.5 GHz, Ta= +25 °C



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